SCBS203D - AUGUST 1992 - REVISED JANUARY 1998

- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- Two 8-Bit Back-to-Back Registers Store **Data Flowing in Both Directions**
- **Noninverting Outputs**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

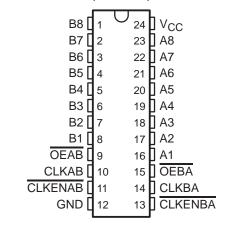
description

The 'ABT2952A transceivers consist of two 8-bit back-to-back registers that store data flowing in both directions between two bidirectional buses. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable (CLKENAB or CLKENBA) input is low. Taking the output-enable (OEAB or OEBA) input low accesses the data on either port.

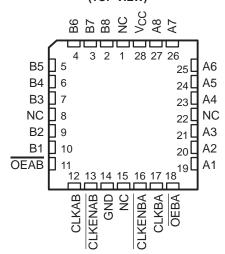
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT2952A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT2952A is characterized for operation from -40°C to 85°C.

SN54ABT2952A . . . JT OR W PACKAGE SN74ABT2952A...DB, DW, PW, OR NT PACKAGE (TOP VIEW)



SN54ABT2952A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



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SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

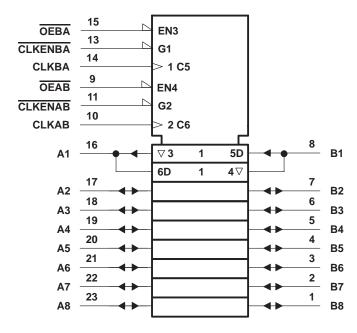
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FUNCTION TABLE†

	INPUTS										
CLKENAB	CLKAB	OEAB	Α	В							
Н	Х	L	Х	в ₀ ‡							
Х	H or L	L	Χ	в ₀ ‡ в ₀ ‡							
L	\uparrow	L	L	L							
L	\uparrow	L	Н	Н							
Х	Χ	Н	Χ	Z							

[†]A-to-B data flow is shown; B-to-A data flow is similar, but uses CLKENBA, CLKBA, and OEBA.

logic symbol§



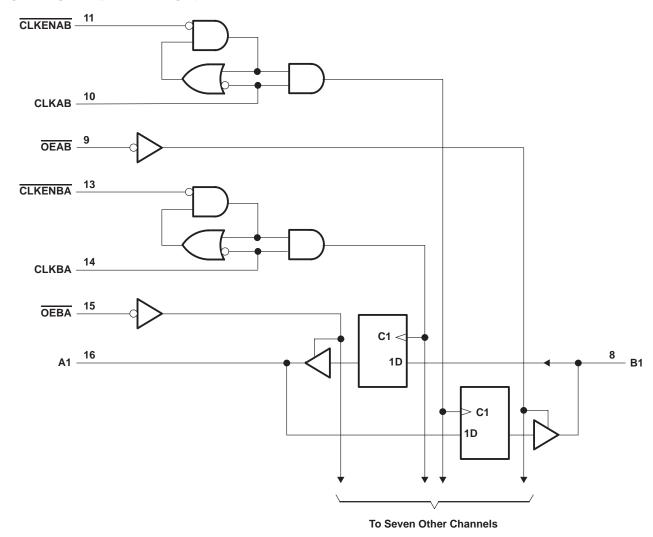
§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.



[‡]Level of B before the indicated steady-state input conditions were established

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logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		. -0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Not		
Voltage range applied to any output in the high or	power-off state, VO	-0.5 V to 5.5 V
Current into any output in the low state, Io: SN54/	ABT2952A	96 mA
SN74/	ABT2952A	128 mA
Input clamp current, I _{IK} (V _I < 0)		–18 mA
Output clamp current, I _{OK} (V _O < 0)		–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DI	B package	104°C/W
Di	W package	81°C/W
N	T package	67°C/W
P\	W package	120°C/W
Storage temperature range, T _{stq}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT	2952A	SN74ABT	2952A	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage	2		2		V	
VIL	Low-level input voltage		0.8		0.8	V	
٧ı	Input voltage		0	VCC	0	VCC	V
IOH	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		– 55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAME	TED	TEST CO	ONDITIONS	Т	A = 25°C	;	SN54AB1	Г2952A	SN74ABT	2952A	UNIT	
PARAME	IIEK	1231 00	CNUTTONS	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	Voн		$I_{OH} = -3 \text{ mA}$	3			3		3		V	
[∨] OH			$I_{OH} = -24 \text{ mA}$	2			2				v	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2			
VOL		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V	
VOL		VCC = 4.5 V	I _{OL} = 64 mA			0.55*				0.55	V	
V _{hys}					100						mV	
	trol inputs	V _{CC} = 5.5 V,	V _I = V _{CC} or GND			±1		±1		±1	μΑ	
II A or	A or B ports		1 = 100 01 014D			±100		±100		±100	μι	
lozh [‡]		$V_{CC} = 5.5 V$,	$V_0 = 2.7 \text{ V}$			50*		10		50	μΑ	
lozL [‡]		$V_{CC} = 5.5 V$,	$V_0 = 0.5 V$			-50*		-10		-50	μΑ	
l _{off}		$V_{CC} = 0$,	= 0, V_I or $V_O \le 4.5 \text{ V}$			±100*				±100	μΑ	
ICEX		V _C C = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μА	
IO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
		$V_{CC} = 5.5 V,$	Outputs high		1	250		250		250	μΑ	
I _{CC} A or	B ports	$I_O = 0$, $V_I = V_{CC}$ or	Outputs low		24	35		35		35	mA	
		GND	Outputs disabled		0.5	250		250		250	μΑ	
ΔICC¶		V _{CC} = 5.5 V, One Other inputs at V _C			1.5		1.5		1.5	mA		
C _i Con	trol inputs	V _I = 2.5 V or 0.5 \	/		3.5						pF	
C _{io} A or	B ports	V _O = 2.5 V or 0.5	V		7.5						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				V _{CC} =	= 5 V, 25°C	SN54AB1	Γ2952A	SN74ABT	UNIT		
				MIN	MAX	MIN	MAX	MIN	MAX		
fclock	Clock frequency	0	150	0	150	0	150	MHz			
t _W	Pulse duration, CLK high or low	3.3		3.3		3.3		ns			
	Setup time before CLK↑	A or B	High or low	2.5		3		2.5		no	
t _{su}		CLKEN	High or low	3		3		3		ns	
4.	Hold time after CLK↑	A or B		1.5		1.5		1.5			
t _h	Hold time after CLK	CLKEN		2		2		2		ns	

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current. § Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

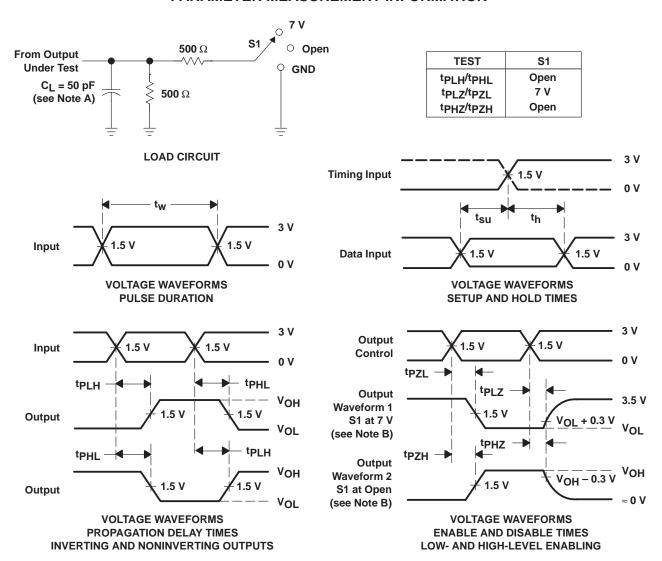
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V A = 25°C	', ;	SN54AB1	^{2952A}	SN74AB1	UNIT	
	(INFOT)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			150			150		150		MHz
^t PLH	CLKAD or CLKDA	B or A	2	3.3	5.2	2	6.3	2	5.9	ns
^t PHL	CLKAB or CLKBA		2.5	4	6.1	2.5	6.8	2.5	6.3	115
^t PZH	OFDA AT OFAR	A or B	1.5	3.2	4.7	1.5	5.7	1.5	5.6	ns
tpZL	OEBA or OEAB	AUIB	2	3.7	5.7	2	6.7	2	6.6	115
^t PHZ	OFDA - OFAR	A or B	1.5	3.5	5.1	1.5	6.5	1.5	6.4	no
tPLZ	OEBA or OEAB		1.5	3.4	5.9	1.5	6.7	1.5	6.2	ns



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





4-Feb-2021

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9308602QLA	ACTIVE	CDIP	JT	24	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9308602QL A SNJ54ABT2952AJ T	Samples
SN74ABT2952ADWR	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT2952A	Samples
SNJ54ABT2952AJT	ACTIVE	CDIP	JT	24	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9308602QL A SNJ54ABT2952AJ T	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

4-Feb-2021

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OTHER QUALIFIED VERSIONS OF SN54ABT2952A, SN74ABT2952A:

Catalog: SN74ABT2952A

Military: SN54ABT2952A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





_		
		Dimension designed to accommodate the component width
	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
ı	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT2952ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74ABT2952ADWR	SOIC	DW	24	2000	350.0	350.0	43.0	

JT (R-GDIP-T**)

24 LEADS SHOWN

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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